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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/676,645	10/01/2003	Gyung-Su Cho	PPW06-563DS	7874
36872	7590	06/01/2007	EXAMINER	
THE LAW OFFICES OF ANDREW D. FORTNEY, PH.D., P.C. 401 W FALLBROOK AVE STE 204 FRESNO, CA 93711-5835			NADAV, ORI	
			ART UNIT	PAPER NUMBER
			2811	
			MAIL DATE	DELIVERY MODE
			06/01/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No.	Applicant(s)
	10/676,645	CHO, GYUNG-SU
Examiner	Art Unit	
Ori Nadav	2811	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1) Responsive to communication(s) filed on 08 March 2007.

2a) This action is **FINAL**. 2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4) Claim(s) 1,4,5,8,22-24,27-32 and 34-37 is/are pending in the application.
4a) Of the above claim(s) _____ is/are withdrawn from consideration.

5) Claim(s) _____ is/are allowed.

6) Claim(s) 1,4,5,8,22-24,27-32 and 34-37 is/are rejected.

7) Claim(s) _____ is/are objected to.

8) Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on _____ is/are: a) accepted or b) objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
a) All b) Some * c) None of:
1. Certified copies of the priority documents have been received.
2. Certified copies of the priority documents have been received in Application No. _____.
3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) Notice of References Cited (PTO-892) 4) Interview Summary (PTO-413)
2) Notice of Draftsperson's Patent Drawing Review (PTO-948) Paper No(s)/Mail Date. ____.
3) Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date ____.
5) Notice of Informal Patent Application
6) Other: ____.

DETAILED ACTION***Specification***

The title of the invention is not descriptive. A new title is required that is clearly indicative of the invention to which the claims are directed.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1, 4-5, 23-24, 27-32 and 34-37 are rejected under 35 U.S.C. 102(e) as being anticipated by Matsubara (6,890,852).

Matsubara teaches in figure 1 and related text a semiconductor device comprising:

a via within an insulation layer 16 over a semiconductor substrate 1;

a barrier metal layer 6 on a surface of the via;

a metal line 9 comprising copper in the via over the barrier metal layer; and

a pad 13 in a predetermined region of the metal line; and

an alloy layer 10 (column 10, lines 20-22) on an upper surface of the metal line,

wherein a top surface of the alloy layer is coplanar with or lower than a top surface of

the insulation layer, and the alloy layer comprises copper and a low melting point metal selected from the group consisting of aluminum, lead, and silver, wherein

the thickness of the alloy layer is less than a thickness of the metal line, wherein

a protection layer 26 (see figure 12) comprising silicon nitride or silicon oxynitride

on the metal line except for the predetermined region, wherein

the barrier metal comprises a metal selected from the group consisting of Ti, Ta,

TiN, and TaN, and having a thickness between 200 and 800A

an insulation layer 101 comprises oxide over the semiconductor device, wherein

the via is within the insulation layer, wherein

the barrier metal layer prevents the diffusion of copper from the metal line into

the substrate, wherein

the alloy layer is completely within the via and exposed through an opening in the

protection layer, wherein

the barrier metal layer covers all surfaces of the via and contacts the substrate,

and

wherein a thickness of the alloy layer being less than a thickness of the metal line.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the

invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 8 and 22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Matsubara in view of Liu et al. (6,638,867).

Regarding claims 5 and 22, Matsubara teaches in figure 1 and related text substantially the entire claimed structure, as applied to claim 1 above, except a width of the pad is less than a width of via.

Liu et al. teach in figure 2 and related text a width of the pad 24 is less than a width of via.

It would have been obvious to a person of ordinary skill in the art at the time the invention was made to use a width of the pad being less than a width of via in Matsubara's device in order to reduce the size of the device.

Response to Arguments

Applicant argues that Matsubara does not teach an alloy layer comprises copper and a low melting point metal selected from the group consisting of aluminum, lead, and silver.

Matsubara clearly teaches in column 10, lines 20-22 an alloy layer comprises copper and a low melting point metal selected from the group consisting of aluminum, lead, and silver.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Ori Nadav whose telephone number is 571-272-1660. The examiner can normally be reached between the hours of 7 AM to 4 PM (Eastern Standard Time) Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Richard Elms can be reached on 571-272-1869. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



O.N.
5/27/07

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